

HSP

NOTES:

Current Rating: 3.0AMP
 Withstand Voltage: 500V AC/DC
 Contact Resistance: 20mΩ Max
 Insulation Resistance: 1000MΩMin
 Operation Temperature: -40°C to +105°C

Contact Material: Phosphor Bronze
 Contact plating: Au or Sn over Ni
 Insulator Material: PA6T or PBT+30%G.F UL94V-0

Ordering Information

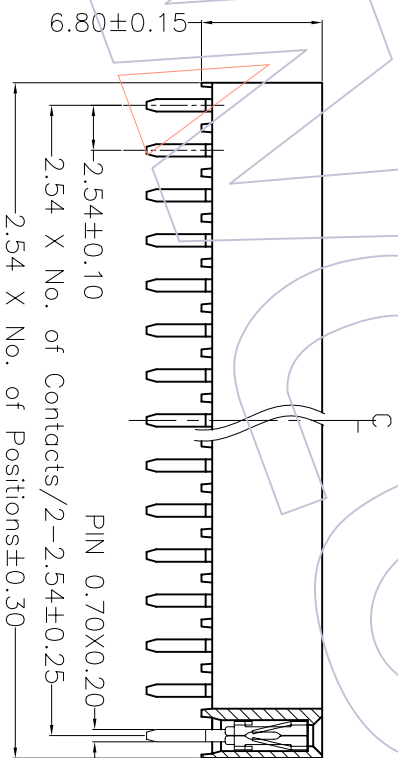
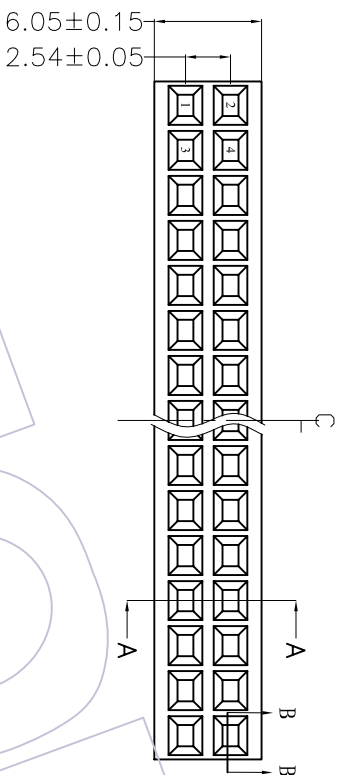
2168 - 2 XX S XX X UN T1

No. of Pins per ROW: 02-40PIN

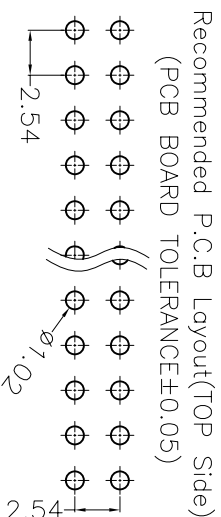
Contact Plating: GO=Gold Flash
 GH=3μ"Gold
 GS=5μ"Gold
 G3=10μ"Gold
 G4=15μ"Gold
 G5=30μ"Gold
 SO=Gold Flash,Tin
 SI=3μ"Gold,Tin
 S2=5μ"Gold,Tin
 S3=10μ"Gold,Tin
 S4=15μ"Gold,Tin
 S5=30μ"Gold,Tin
 SN=Tin

Insulator: A=PBT
 C=PA6T

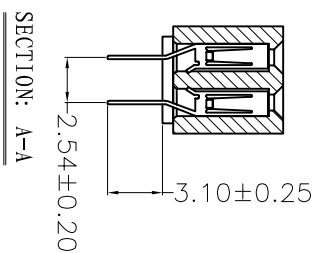
Packaging: T=Tube



SECTION: B-B



Recommended P.C.B Layout(TOP Side)
 (PCB BOARD TOLERANCE±0.05)



SECTION: A-A

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	OPERATION	DRAW	WEIXD	SCALE	PART NO.
A0	08/03/12	NEW			X.X ±0.40	DESIGN	08.03.12	2.5:1	2168-2XXSXXXUNT1
					X.XX ±0.25	CHECK			FH2.54 DUAL 180° H=6.8
					X.XXX ±0.15	APPROVE			
					Angle ± 3'				
					DIM TOL				

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 WAFER HARDWARE ELECTRONICS CO.,LTD